

MW-G

- MW-G 銅箔係適用於Hi-Tg及無鹵素基板之符合新一代環保要求之電解銅箔。
MW-G copper foil comply with environment regulation is especially suitable for Hi-Tg and Halogen Free prepregs.
- 具優良的抗撕強度/極佳的耐熱性/優越的蝕刻性。
Good bonding strength./ Excellent heat resistance./ Good etchability.
- 9 μ m之薄銅箔穩定的量產能力, 可充分供應客戶需求。
Our plant has stable capacity for 9 μ m thin foil to fulfill customer requirements.

用途/Application

- 適用於多層印刷電路板(HDI)
/High Density Interconnect(HDI)
- 封裝載板(薄銅)
/Semiconductor Package(thin copper foil)

結構/Composition



生產地點/Production Site

- 台灣 / Taiwan
- 馬來西亞 / Malaysia

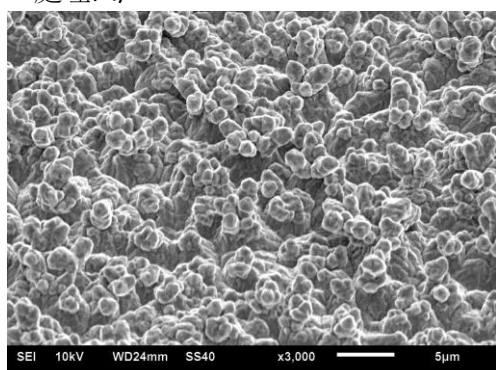
特性代表值/Representative data

	μ m	Rz (μ m)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)
MW-G	9	3.8	370	4	0.9
	12	4.2	370	6	1.2
	18	4.5	370	8	1.4
	35	6.5	370	16	1.8
	70	12.5	300	19	2.5

※上述表列為代表性數據非保證值。

This is representative data, not guarantee.

處理面/Laminate side



阻劑面/ Resist side

